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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10063915	FILING DATE 05/23/2002	CLASS 228	SUBCLASS 245	GAU 1725	EXAMINER McHenry
<b>**APPLICANTS:</b> Sakai Hiroshi; Suzuki Motoji; Igarashi Makoto; Tanaka Akihiro;					
<b>**CONTINUING DATA VERIFIED:</b> Km					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> Km JAPAN 2001-166910 06/01/2001					
PG-PUB <input type="checkbox"/>		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input checked="" type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 15574	
Verified and Acknowledged Examiners's initials Km					
TITLE : Solder paste printing method and apparatus for printing solder paste on a board on which wiring patterns are formed					
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)					

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	Print Claim for O.G.
<b>ISSUE FEE</b>		<b>DRAWING</b>	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		Application Examiner	
		<b>PREPARED FOR ISSUE</b>	
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